

Anti-Tombstoning Solder Paste

Introduction

FCT Assembly offers a variety of anti-tombstoning solder pastes as an option with each of our solder paste fluxes. These solder pastes are an excellent choice to reduce the potential for tombstoning and skewing. They also provide an added benefit of reducing the potential for voiding. The anti-tombstoning solder pastes are made with a blend of solder alloys which gives the solder paste a wider melting range. This slows the melting rate allowing more time to equalize the wetting forces between solder joints of susceptible components.

Attributes

- Dramatic improvement in tombstoning and skewing.
- Minimizes the potential for voiding.
- Utilizes the same solder paste fluxes as standard versions of the solder pastes.

Solder Alloy Mixtures (% weight)	Solder Alloy Letter Code	Solder Powder Size Availability (IPC J-STD-005)	Melting Range (°C)	Intended for which solder pastes?
90% Sn63/Pb37 + 10% Sn62/Pb36/Ag2	AB	Type 3 or 4	179 to 183	Sn63/Pb37
80% Sn63/Pb37 + 20% Sn62/Pb36/Ag2	T	Type 3 or 4	179 to 183	Sn63/Pb37
90% SAC305 + 10% SN100C	Y	Type 3 or 4	217 to 227	SAC305
80% SAC305 + 20% SN100C		Type 3 or 4	217 to 227	SAC305
90% Sn/Ag3.5 + 10% SN100C	W	Type 3	221 to 227	Sn/Ag3.5
90% SN100C* + 10% SAC305	R	Type 3 or 4	217 to 227	SN100C*
90% SN100CV* + 10% SAC305		Type 3 or 4	217 to 225	SN100CV*

- Other sizes of solder powder are available upon request.
- *Alloy from Nihon Superior.

The solder alloy mixture chosen is based upon the solder paste that is currently in use. The solder alloy in the currently used solder paste should be the main (90% or 80%) constituent of the anti-tombstoning solder alloy chosen. For example, if tombstoning is occurring with a Sn63/Pb37 solder paste, then either the 90% Sn63/Pb37 + 10% Sn62/Pb36/Ag2 or the 80% Sn63/Pb37 + 20% Sn62/Pb36/Ag2 anti-tombstoning mixtures are recommended.

Stencil Design

Our stencil partner, BlueRing Stencils can provide several design modifications which are effective at reducing the potential for tombstoning and skewing. In some cases, using a modified stencil design along with an anti-tombstoning solder paste may be required to fully resolve the issue.

Reflow Profile

Reflow profile modifications can help to reduce the potential for tombstoning but are best used along with anti-tombstoning solder pastes in order to minimize the potential for tombstoning. Addition of extra soak time may help:

- Tin-lead solder pastes - add 15-30 seconds of time between 150 and 170 °C.
- Lead-free solder pastes - add 15-30 seconds of time between 180 and 200 °C.

Other Information

Please refer to the Technical data sheet (TDS) and Safety Data Sheet (SDS) for each solder paste for additional details.

Limited Liability and Warranty Disclaimer

All information, statements, technical data, and recommendations contained in this Technical Data Sheet are based on testing we believe to be reliable. However, the accuracy or completeness thereof is not guaranteed. It is impossible for our lab to account for all manufacturing conditions and variables. Products are warranted to be free from defects at the time sold. To the full extent consistent with applicable law, the exclusive remedy of the user or buyer is to receive replacement product for any product defective at the time sold. FCT Assembly, Inc. makes NO WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. Further, FCT Assembly, Inc. makes no other express, implied, or statutory warranties unless otherwise specified in writing and signed by officers of the corporation.